



**Part Number :** [744410001](#)

**Product Description :** 0.80mm Pitch SFP, SFP Plus (SFP+) Host Connector, Z-Axis Pluggable, Right-Angle, Surface Mount, 20 Circuits, 0.38µm Gold (Au)

**Series Number :** 74441

**Status :** Active

**Product Category :** High-Speed I/O Connectors



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## Documents and Resources

### Drawings

[744410001\\_sd.pdf](#)

[PK-70873-1201-001.pdf](#)

### 3D Models and Design Files

[STEP AP242](#)

[SOLIDWORKS](#)

[Creo](#)

[Symbol and Footprint \(Multi-Format\)](#)

[EE-74441-001-001.pdf](#)

[SP-74441-001-001.zip](#)

### Specifications


[AS-74441-001-001.pdf](#)

[PS-74441-001-001.pdf](#)

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## Product Environment Compliance

### Compliance

GADSL/IMDS	Compliant with Exemption 44; 34; 33
China RoHS	 per SJ/T 11365-2006
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2025)7771-DC (04 Feb 2026)

EU RoHS	Compliant per EU 2015/863
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### Compliance Statements

- EU RoHS
- REACH SVHC
- Low-Halogen

### Industry Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

### Substances of Interest

- PFAS

### EU RoHS Certificate of Compliance

### Additional Product Compliance Information

## Part Details

### General

Status	Active
Category	High-Speed I/O Connectors
Series	74441
Description	0.80mm Pitch SFP, SFP Plus (SFP+) Host Connector, Z-Axis Pluggable, Right-Angle, Surface Mount, 20 Circuits, 0.38µm Gold (Au)
Application	Module-to-Board
Component Type	Receptacle
Product Name	SFP,SFP Plus,SFP+
Type	Pluggable
UPC	800755998788

### Agency

CSA	LR19980
UL	E29179

### Electrical

Current - Maximum per Contact	0.5A
Data Rate	10.0 Gbps, 28.0 Gbps
Grounding to Panel	Yes
Shielded	No
Voltage - Maximum	30V AC (RMS)/DC

## Physical

Boot Color	N/A
Circuits Detail	20
Circuits (Loaded)	20
Circuits (maximum)	20
Color - Resin	Black
Durability (mating cycles max)	200
Flammability	94V-0
Gender	Receptacle
Keying to Mating Part	Yes
Lock to Mating Part	Yes
Material - Metal	High Performance Alloy (HPA)
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	0.600/g
Number of Rows	2
Orientation	Right Angle
Packaging Type	Embossed Tape on Reel
Panel Mount	No
PCB Locator	Yes
PCB Retention	Yes
Pitch - Mating Interface	0.80mm
Pitch - Termination Interface	0.80mm
Plating min - Mating	0.381µm
Plating min - Termination	2.540µm
Polarized to Mating Part	Yes
Polarized to PCB	No
Ports	1

Temperature Range - Operating	-40° to +85°C
Termination Interface Style	Surface Mount
Waterproof / Dustproof	No
Wire Size (AWG)	N/A

### Solder Process Data

Max-Duration	40
Lead-Free Process Capability	REFLOW
Max-Cycle	3
Max-Temp	260

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### Mates With / Use With

#### Mates with Part(s)

Description	Part Number
Mates With	SFP Modules

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